

/ Descriptions

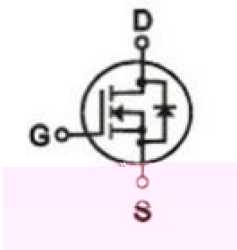
/ Features

$\leq \Omega \quad \Omega$

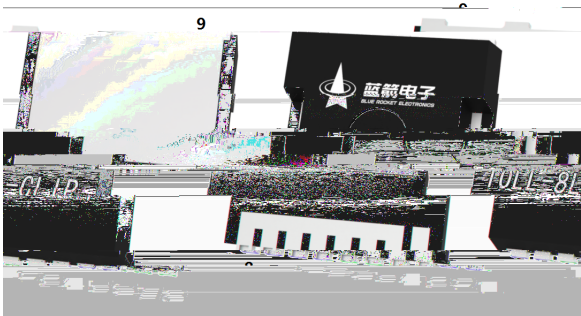
/ Applications

BMS

/ Equivalent Circuit



/ Pinning



/ Marking

/ Absolute Maximum Ratings($T_C=25^\circ\text{C}$)[illegible]

Note 1 Surface Mounted on 1 in² pad area, t ≤ 10 sec.

Note 2 Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

Note 3 Limited by bonding wire.

/ Electrical Characteristics(Ta=25)

						Ω

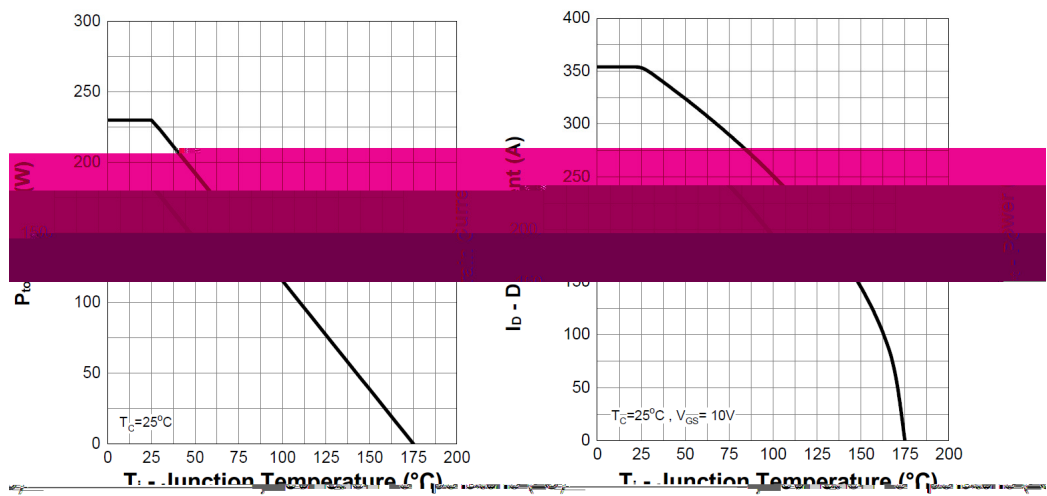
/ Electrical Characteristics(Ta=25)

		Ω Ω				
		$I_{DS} = 50\text{ A}, V_{GS} = 0\text{ V}$				
		$dI_{SD}/dt = 100\text{ A}/\mu\text{s}$				

Note 1 Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

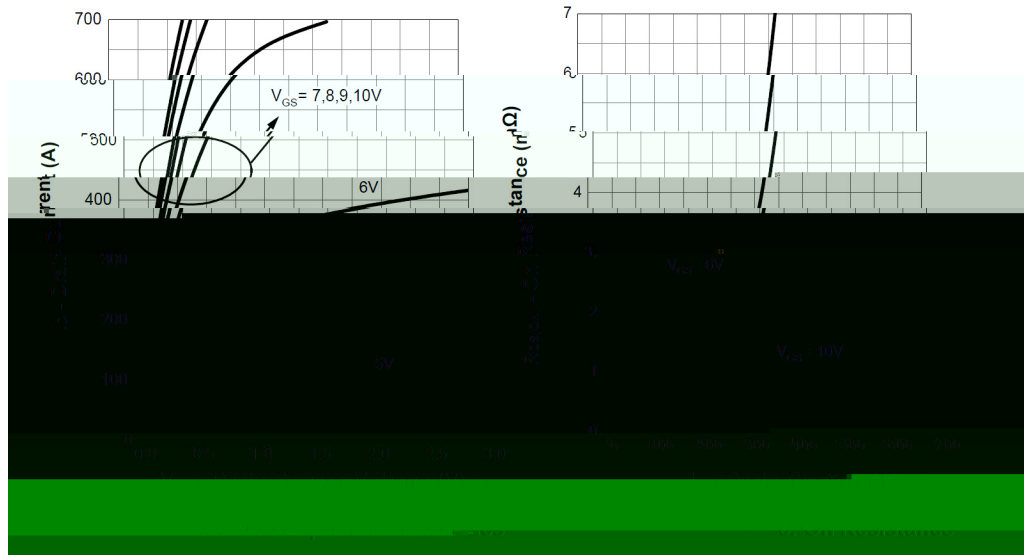
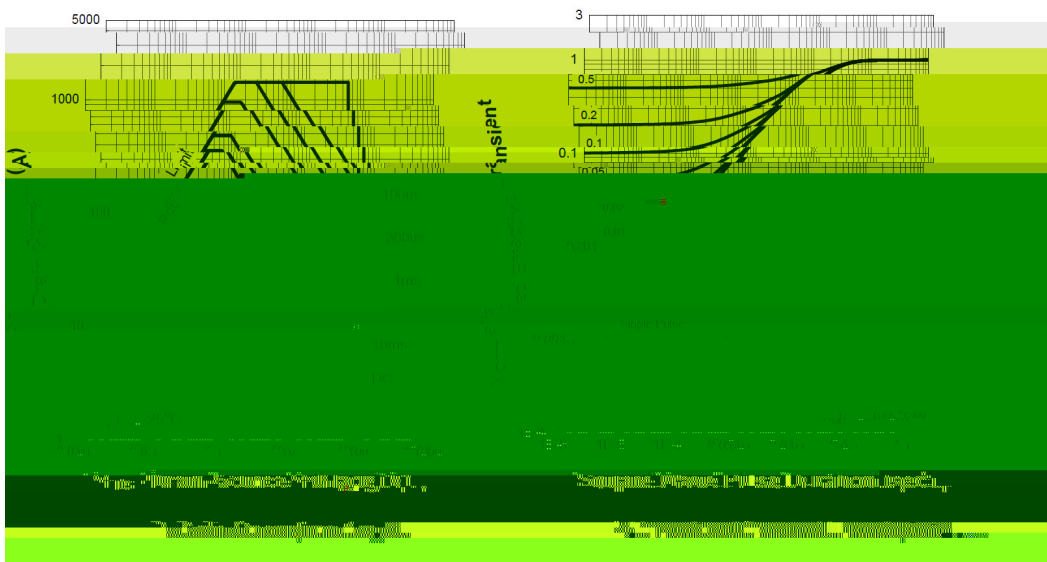
Note 2 Guaranteed by design, not subject to production testing.

/ Electrical Characteristic Curve

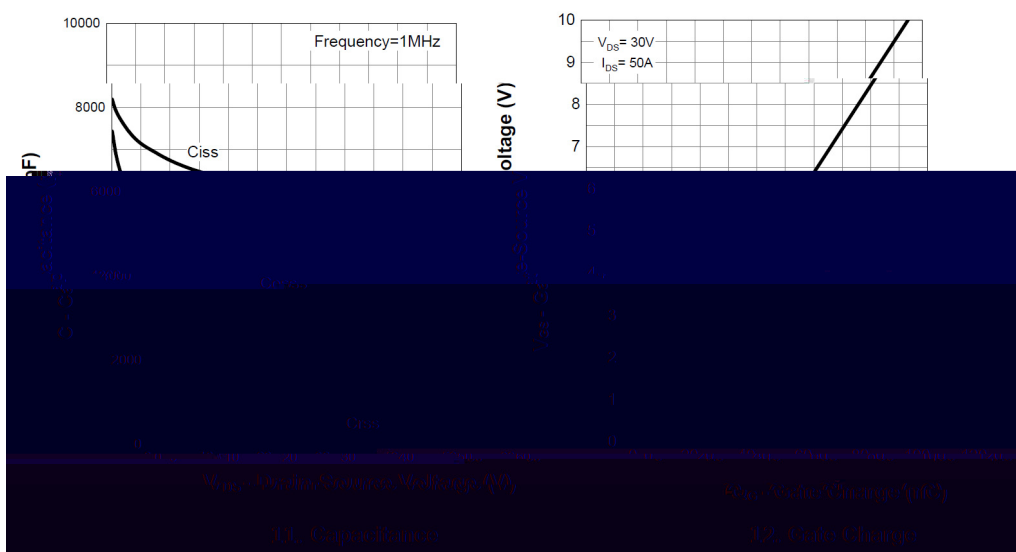
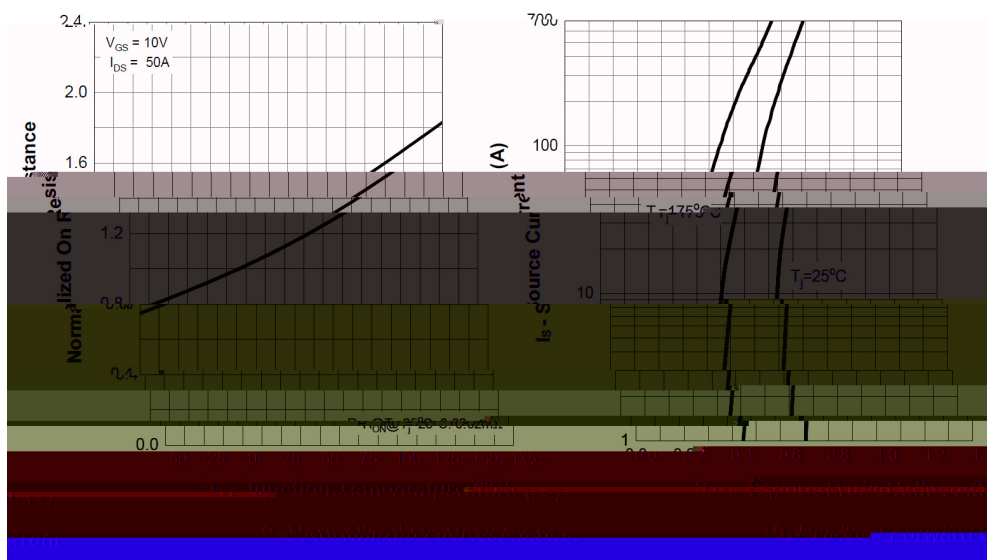
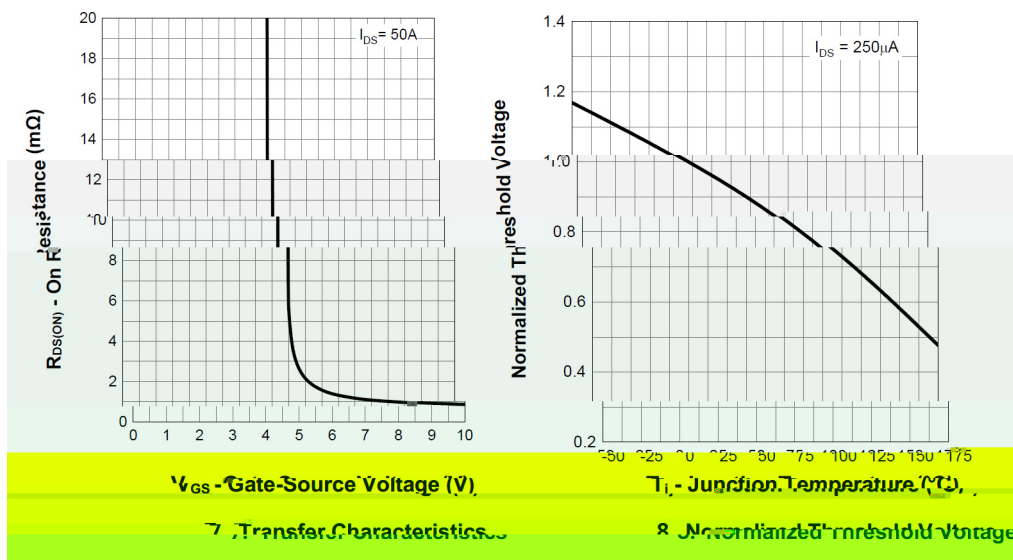


1. Power Capability

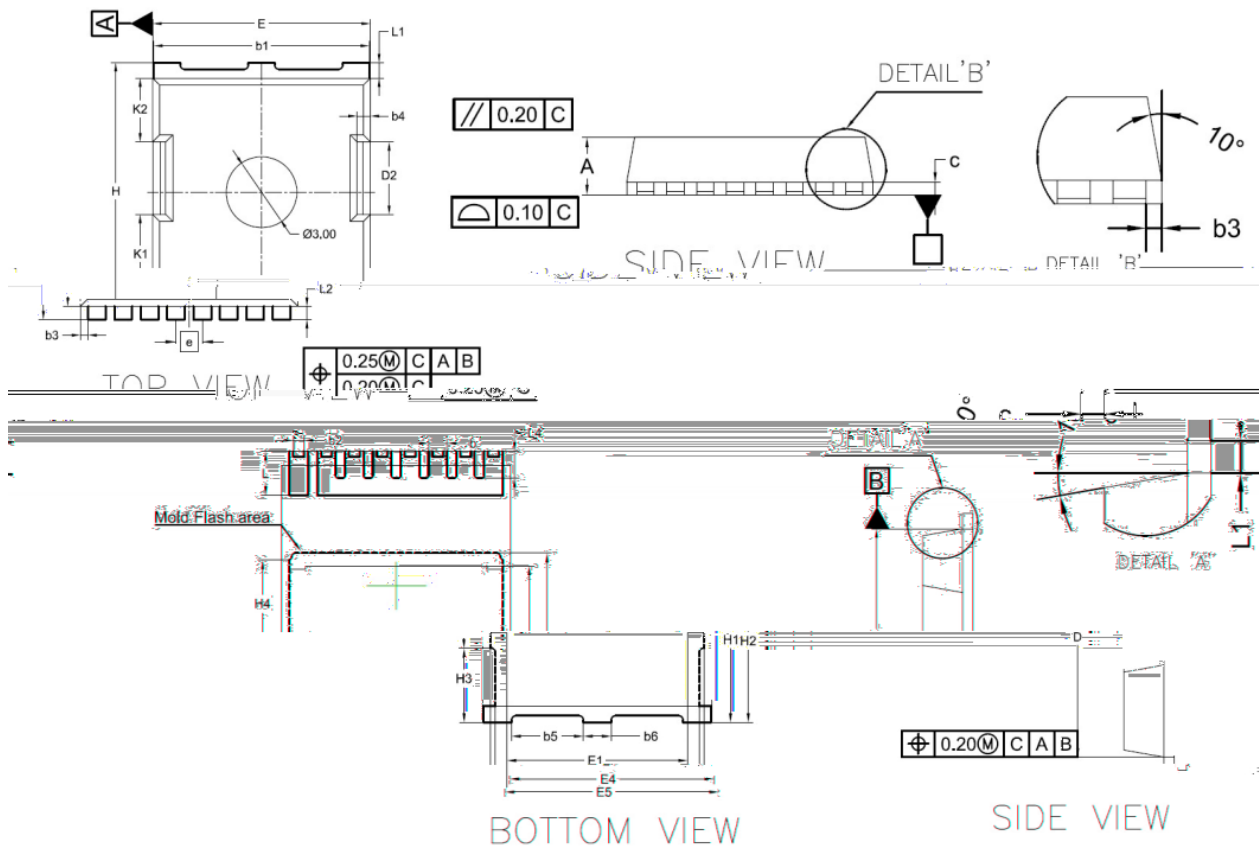
2. Current Capability



/ Electrical Characteristic Curve

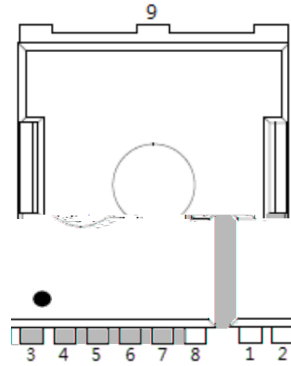


/ Package Dimensions



Symbol	Dimensions In Millimeters			Symbol	Dimensions In Millimeters		
	MIN.	NOM.	MAX.		MIN.	NOM.	MAX.
A	2.200	2.300	2.400	b1	9.700	9.800	9.900
c	0.492	0.500	0.508	b1	0.420	0.460	0.500
D	10.280	10.380	10.480	b3	0.350		
E	9.800	9.900	10.000	b4	0.600		
e	1.20 BSC			b5	3.100		
H	11.580	11.680	11.780	b6	1.200		
H1	6.650	6.750	6.850	L	1.700	1.900	2.100
H2	7.300			L1	0.700		
H3	3.200			L2	0.600		
H4	3.800			L4	1.050	1.150	1.250
K1	4.180			L5	0.500	0.600	0.700
K2	2.900			E1	7.800		
D2	3.300			E4	8.800		
b	0.700	0.800	0.900	E5	9.200		

/ Marking Instructions



BR

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box

/ Notices